

AMPMODU | AMPMODU MICRO

TE Internal #: 1375876-2 AMPMODU MICRO, Connector Contact, Pin, Wire-to-Board, .8mm [.031in] Centerline, 30 – 28AWG Wire Size, 100.5 – 159.8CMA Wire Size

View on TE.com >

Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Connector Contacts



Contact Type: **Pin** Connector System: **Wire-to-Board**

Centerline (Pitch): .8 mm [.031 in]

Wire Size: 100.5 – 159.8 CMA

Features

Product Type Features



| Connector System | Wire-to-Board | |
|--|-------------------------------|--|
| Sealable | No | |
| Connector & Contact Terminates To | Wire & Cable | |
| Configuration Features | | |
| Compatible With Wire & Cable Type | Discrete Wire | |
| Electrical Characteristics | | |
| Dielectric Withstanding Voltage (Max) | 250 VAC | |
| Insulation Resistance | 500 MΩ | |
| Operating Voltage | 30 VAC | |
| Contact Features | | |
| PCB Contact Termination Area Plating Material Thickness | 2.54 – 5.08 μm[100 – 200 μin] | |
| Contact Underplating Material Thickness | 1.27 μm[50 μin] | |
| Wire Contact Termination Area Plating Material Thickness | 1.27 µm | |
| Wire Contact Termination Area Plating Material | Tin | |
| | | |

AMPMODU MICRO, Connector Contact, Pin, Wire-to-Board, .8mm [.031in] Centerline, 30 – 28AWG Wire Size, 100.5 – 159.8CMA Wire Size



| Contact Mating Area Plating Material Thickness | .76 μm[30 μin] |
|--|---------------------------|
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin-Lead |
| Contact Base Material | Phosphor Bronze |
| Contact Type | Pin |
| Contact Mating Area Plating Material | Gold |
| Contact Current Rating (Max) | 1 A |
| Mechanical Attachment | |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | .8 mm[.031 in] |
| Dimensions | |
| Accepts Wire Insulation Diameter Range | .6 mm[.024 in] |
| Wire Size | .05 – .08 mm² |
| Jsage Conditions | |
| Operating Temperature Range | -55 – 85 °C[-65 – 185 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| ndustry Standards | |
| Approved Standards | UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| Agency/Standard | UL |
| UL File Number | E28476 |
| UL Rating | Recognized |
| Packaging Features | |
| Packaging Quantity | 20000 |
| Packaging Method | Package |
| Other | |
| | Use in plug housing. |

Product Compliance

For compliance documentation, visit the product page on TE.com>

AMPMODU MICRO, Connector Contact, Pin, Wire-to-Board, .8mm [.031in] Centerline, 30 – 28AWG Wire Size, 100.5 – 159.8CMA Wire Size



| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Not Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUN 2020 (209) Candidate List Declared Against: JUN 2020 (209) Pb (13% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location. |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Soldor Process Conshility | Not applicable for colder process capability |

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

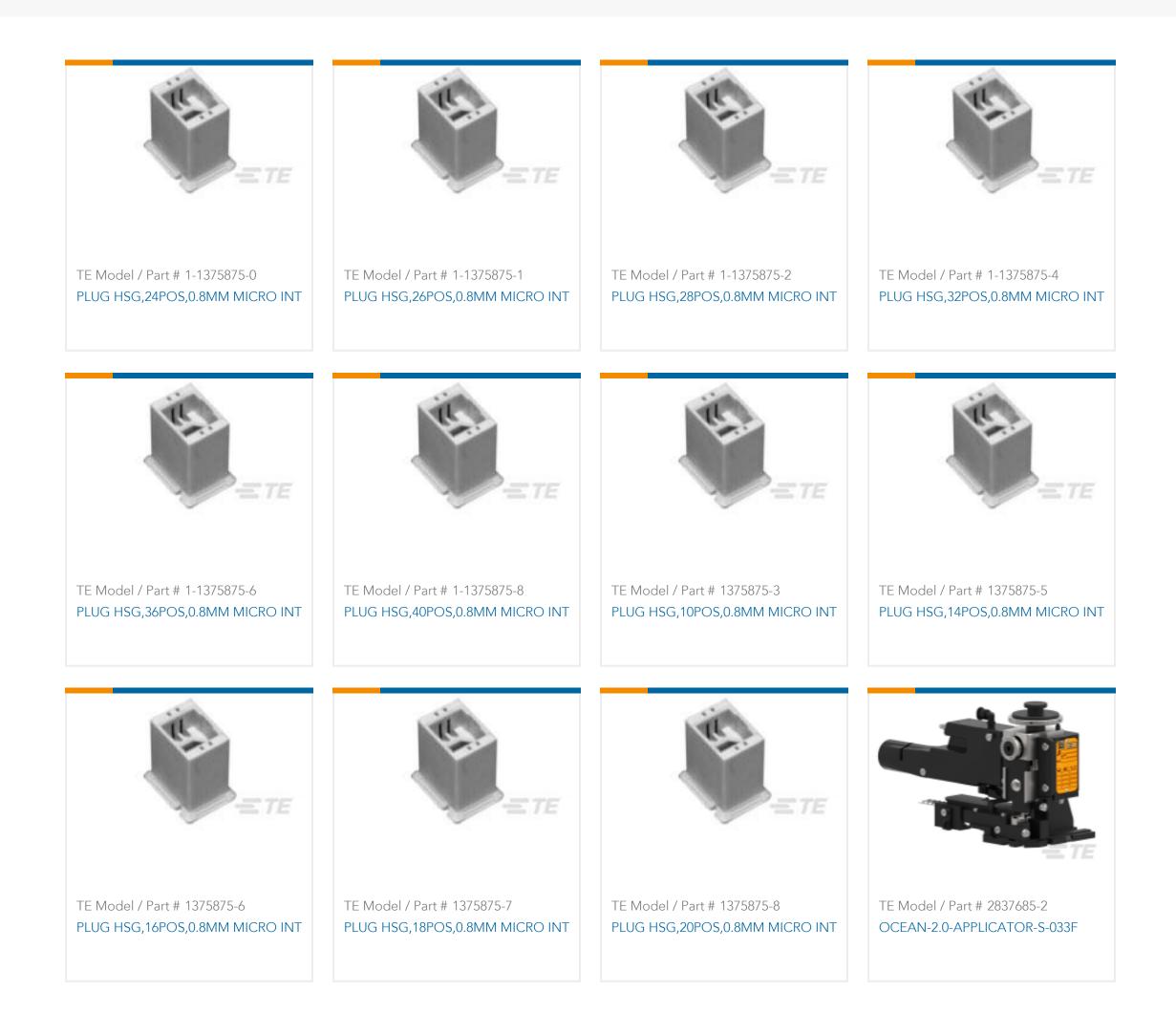
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



AMPMODU MICRO, Connector Contact, Pin, Wire-to-Board, .8mm [.031in] Centerline, 30 – 28AWG Wire Size, 100.5 – 159.8CMA Wire Size





Also in the Series | AMPMODU MICRO

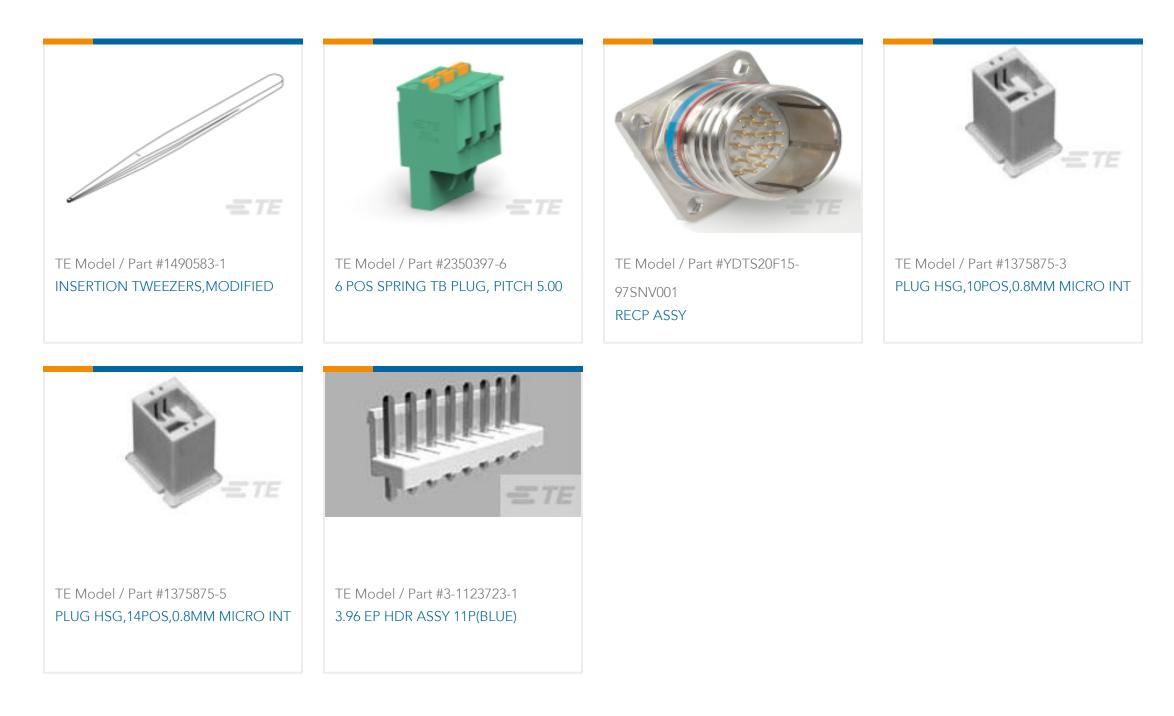
| | | And And And | |
|--------------------------------|--|-------------------------------------|---|
| PCB Connector Strain Relief(2) | Wire-to-Board Connector Assemblies & Housings(15) | Wire-to-Board Connector Contacts(2) | Wire-to-Board Headers & Receptacles (23) |

Customers Also Bought



AMPMODU MICRO, Connector Contact, Pin, Wire-to-Board, .8mm [.031in] Centerline, 30 – 28AWG Wire Size, 100.5 – 159.8CMA Wire Size





Documents

Product Drawings PLUG CONT, PLATED, 0.8MM MIC INT

English

CAD Files **Customer View Model** ENG_CVM_1375876-2_B.2d_dxf.zip

English

Customer View Model

ENG_CVM_1375876-2_B.3d_igs.zip

English

Customer View Model

ENG_CVM_1375876-2_B.3d_stp.zip

English

3D PDF

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English